



Material Content Data Sheet



Sales Product Name		ESD5V3U4U-HDMI E6327		Issued		20. July 2018		
MA#		MA001190924						
Package		PG-TSLP-9-1		Weight*		1.57 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.001	0.09		860	
	non noble metal	tin	7440-31-5	0.000	0.02		222	
	inorganic material	silicon	7440-21-3	0.010	0.64	0.75	6371	7453
leadframe	non noble metal	nickel	7440-02-0	0.330	21.01	21.01	210061	210061
wire	noble metal	gold	7440-57-5	0.043	2.73	2.73	27316	27316
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.001	0.04		351	
	organic material	carbon black	1333-86-4	0.011	0.70		7019	
	plastics	epoxy resin	-	0.149	9.48		94764	
	inorganic material	silicondioxide	60676-86-0	0.943	59.97	70.19	599818	701952
leadfinish	noble metal	gold	7440-57-5	0.032	2.02	2.02	20212	20212
plating	noble metal	silver	7440-22-4	0.052	3.30	3.30	33006	33006
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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